

Title (en)

METHOD OF PROTECTING AN UNDERLYING WIRING LAYER DURING DUAL DAMASCENE PROCESSING

Title (de)

VERFAHREN ZUM SCHUTZ EINER UNTEREN KONTAKTSCHICHT WÄHREND DER HERSTELLUNG EINER DOPPELDAMASZEN-STRUKTUR

Title (fr)

PROCEDE PERMETTANT DE PROTEGER UNE COUCHE DE CABLAGE SOUS-JACENTE LORS D'UN PROCEDE DE DOUBLE DAMASQUINAGE

Publication

**EP 1192656 A1 20020403 (EN)**

Application

**EP 00943434 A 20000605**

Priority

- US 0040108 W 20000605
- US 34558699 A 19990630

Abstract (en)

[origin: WO0101480A1] A method of forming an interconnection including the steps of forming a sacrificial material (160) that comprises a physical property that is generally insensitive to a photoreaction in a via (150) through a dielectric material (130) to a masking material (120) over a conductive material (110). The method also includes forming a trench (180) over in the dielectric material over the via (150) and removing the sacrificial material (160) from the via.

IPC 1-7

**H01L 21/768**

IPC 8 full level

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CPC (source: EP KR)

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**US 0040108 W 20000605**; AU 5790800 A 20000605; EP 00943434 A 20000605; HK 02104146 A 20020531; IL 14730100 A 20000605; IL 14730101 A 20011225; JP 2001506606 A 20000605; KR 20017016608 A 20011224; TW 89112999 A 20000819